

## **Product- information Type: PR33/25,4/SE/MC** Group: Special heatsinks, Finger shaped heatsinks

Special heatsinks

Application (Cases):	TO220 TO218(TOP3)
Number of semiconducters:	1
Mounting of semiconducters :	to clip
Mounting of heatsinks:	to solder
Finish:	black anodized
Thermal resistance:	6.2 K/W
Material:	Aluminium



Special extruded heatsink for semiconductor case TO220; TO218(TOP3).

Standard heights: 25,4, 38,1, 50,8 and 63,5 mm. Version MC (Mounting clip) for clip mounting of semiconductor.

Heatsink solderable by tin plated solder pins.

Also available with distance-/insulating rings, add. IR to the type no.









